

HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH







FEATURES & BENEFITS

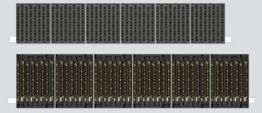
- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and end walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane
- Press-fit extraction and insertion tool options; please visit samtec.com/tooling for details

MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



(Both shown with six 4-pair, 8 column receptacles)

XCede[®] HD

Up to 84 pairs per linear inch

Traditional Backplane

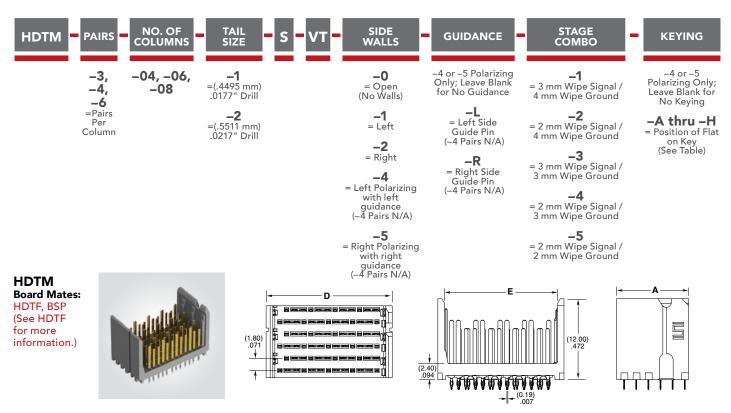
Up to 76 pairs per linear inch

KEY SPECIFICATIONS

PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE
1.80 mm	LCP	Phosphor Bronze (HDTM Series) Copper Alloy (HDTF & HPTS Series)	Au or Sn over 50 μ" (1.27 μm) Ni	-40 °C to + 105 °C (HDTX Series)



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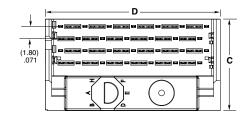


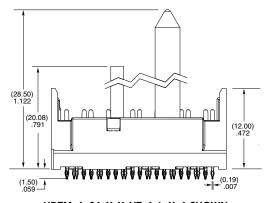
HDTM-4-06-1-S-VT-0-1 SHOWN

NO. OF	Α			С	
COLUMNS	No Walls	Left Wall	Right Wall	Left Polarize	Right Polarize
-04	(7.06) .278	(8.20) .322	(8.06) .317	N/A	N/A
-06	(10.66) .420	(11.80) .465	(11.66) .459	(17.14) .675	(16.65) .656
-08	(14.26) .561	(15.40) .606	(15.26) .600	(20.74) .817	(20.25) .797

PAIRS PER	D	E	
COLUMN	Standard Wall		
-03	(15.10) .594	(13.15) .518	
-04	(18.70) .736	(16.75) .659	
-06	(25.90) 1.020	(23.95) .943	







HDTM-6-04-X-X-VT-4-L-X-A SHOWN

View complete specifications at: samtec.com?HDTM

Notes

Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.